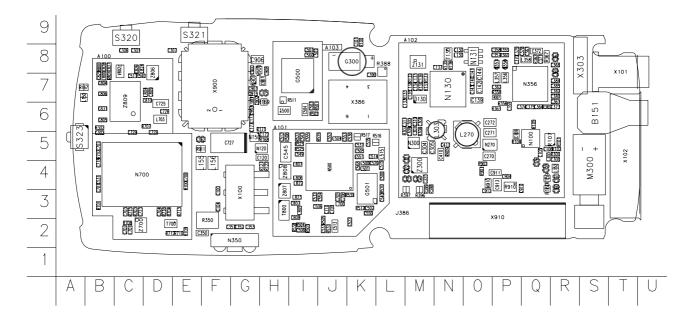


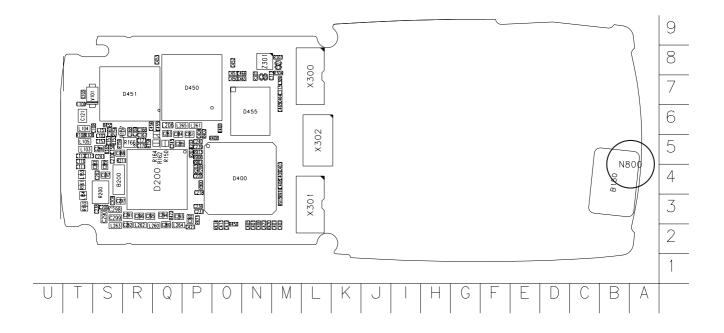
Component layouts

The component layouts are shown in A3 format in the schematics section.

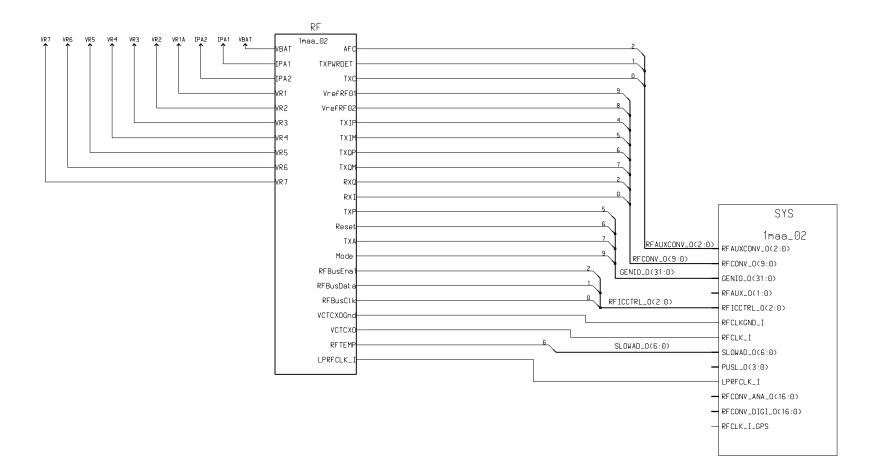
Component layout (top side), 1maa_02



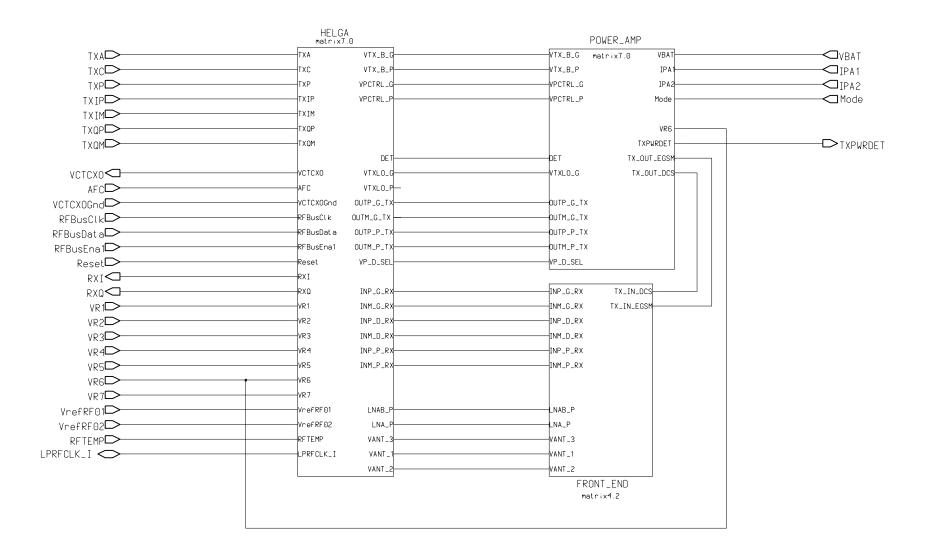
Component layout (bottom side), 1maa_02



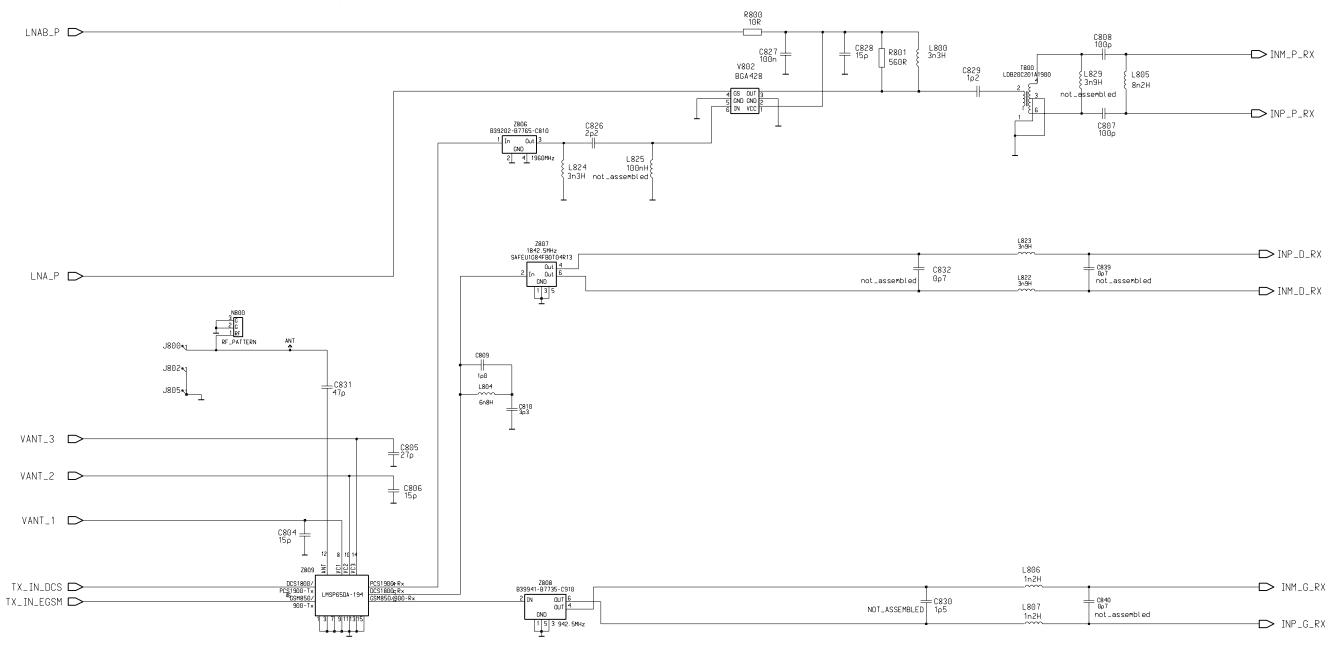
Top Level, 1maa_02, v.0 ed. 40



RF Top Level,1maa_02, v. 0.0 ed. 67



RX Front End and Antenna Switch, 1maa_02, v. 0.0 ed. 79



Last references:

C840

R807

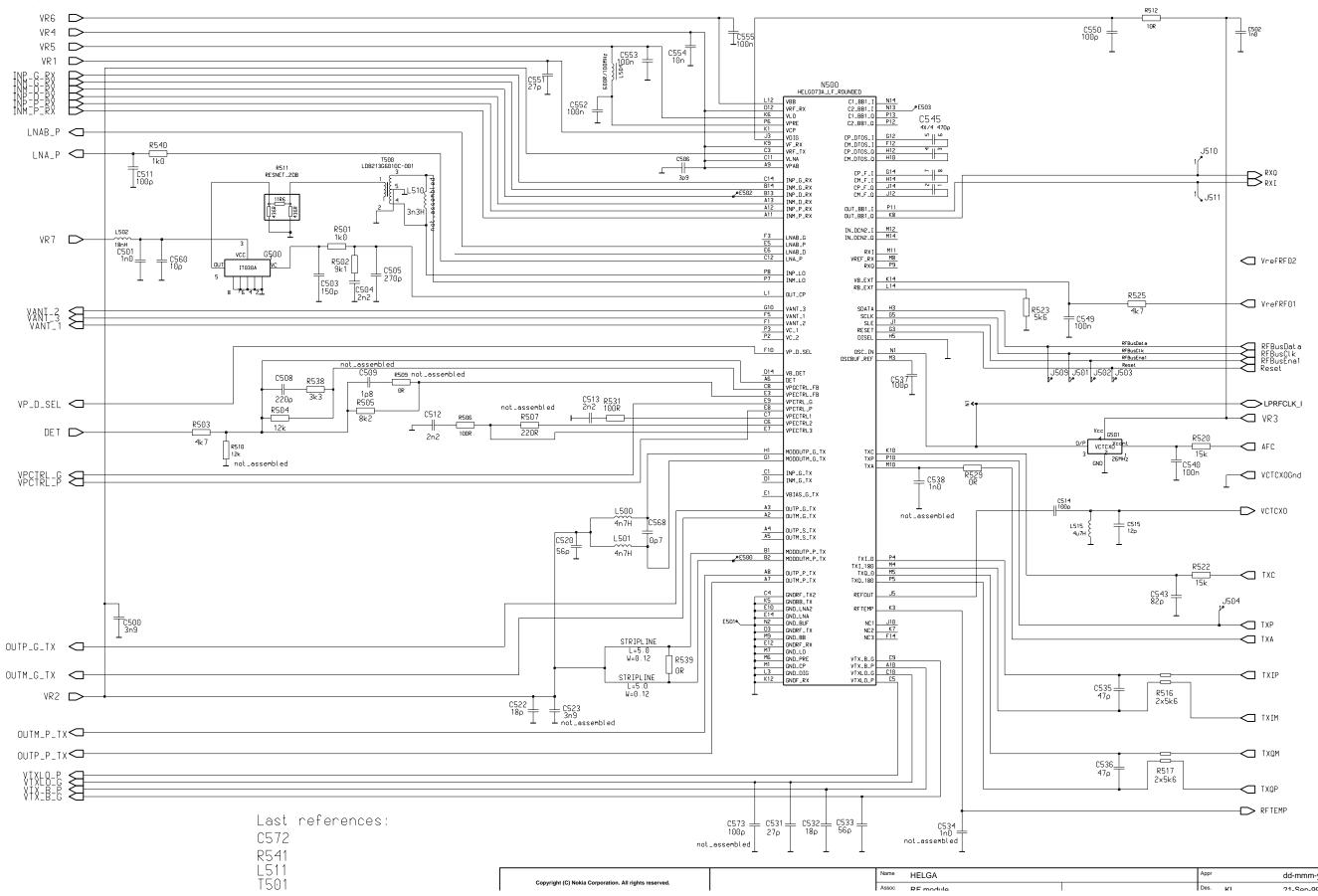
L828

Z809

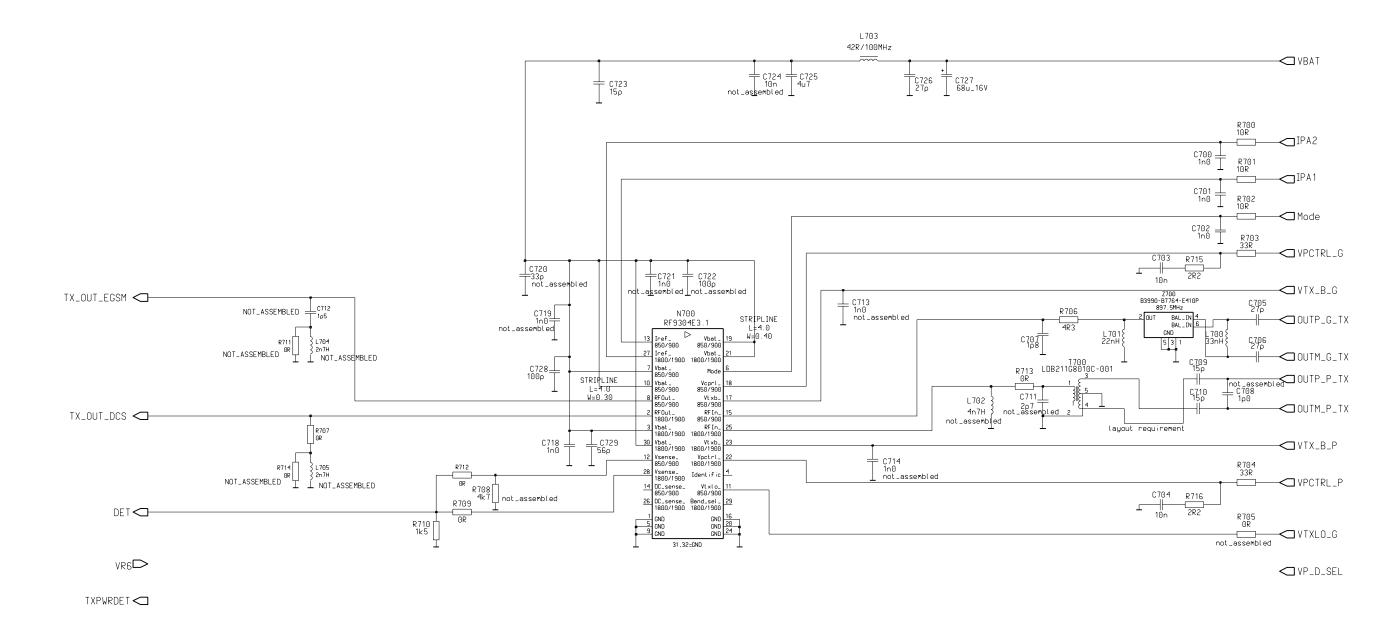
V800

RM-72

HELGA, 1maa_02, ed. 98



RF9204 Power Amplifier and Power Detection, 1maa_02, v. 0.2 ed. 65

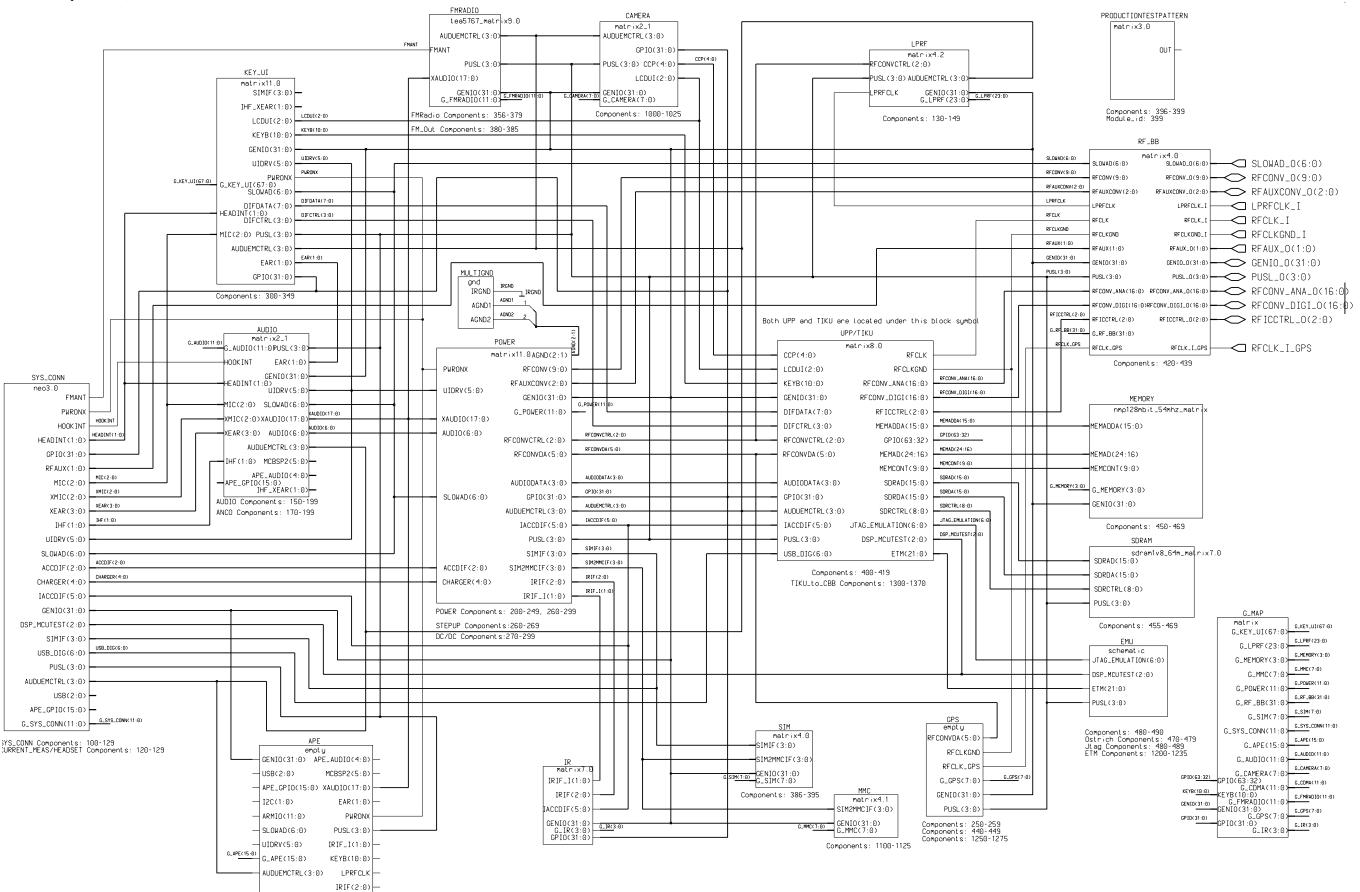


Last references:

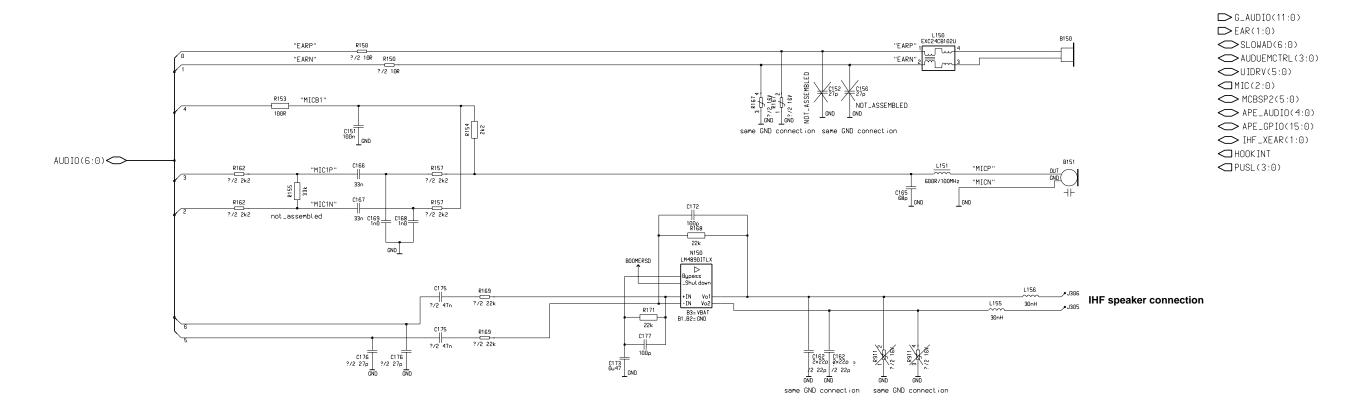
C731

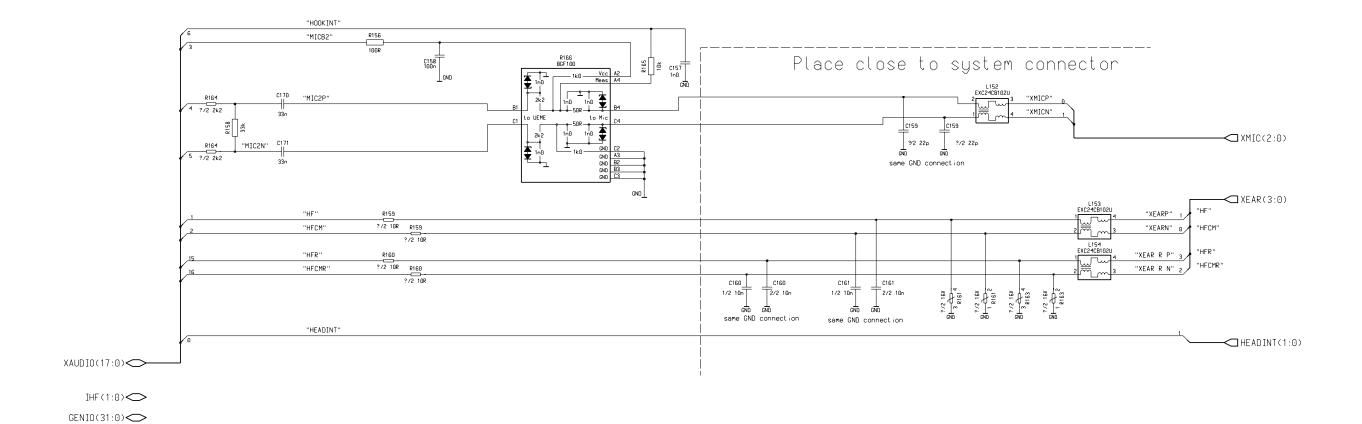
R714 L705

BR4.5 Top Level, 1maa_02, v. 6.1 ed. 43

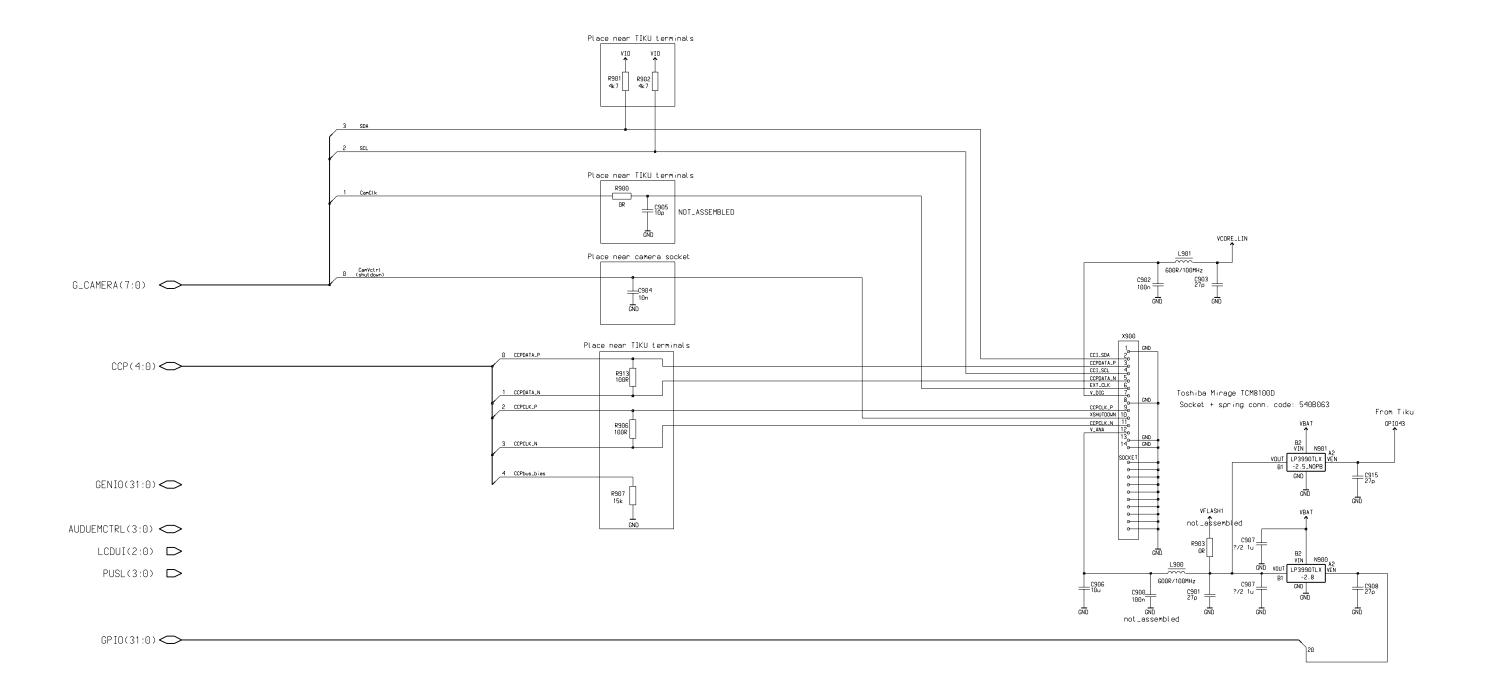


BR45 Audio, 1maa_02, v. 1.6 ed. 190

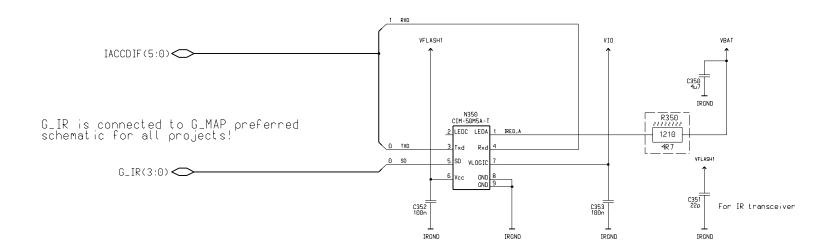




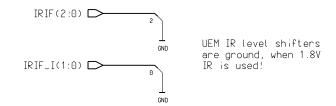
Mirage 2 VGA Camera, 1maa_02, v. 1.1 ed. 206



Citizen IR Module 1.8V, 1maa_02, v. 6.1.8 ed. 56



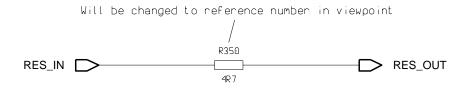
GENIO(31:0) GPIO(31:0)



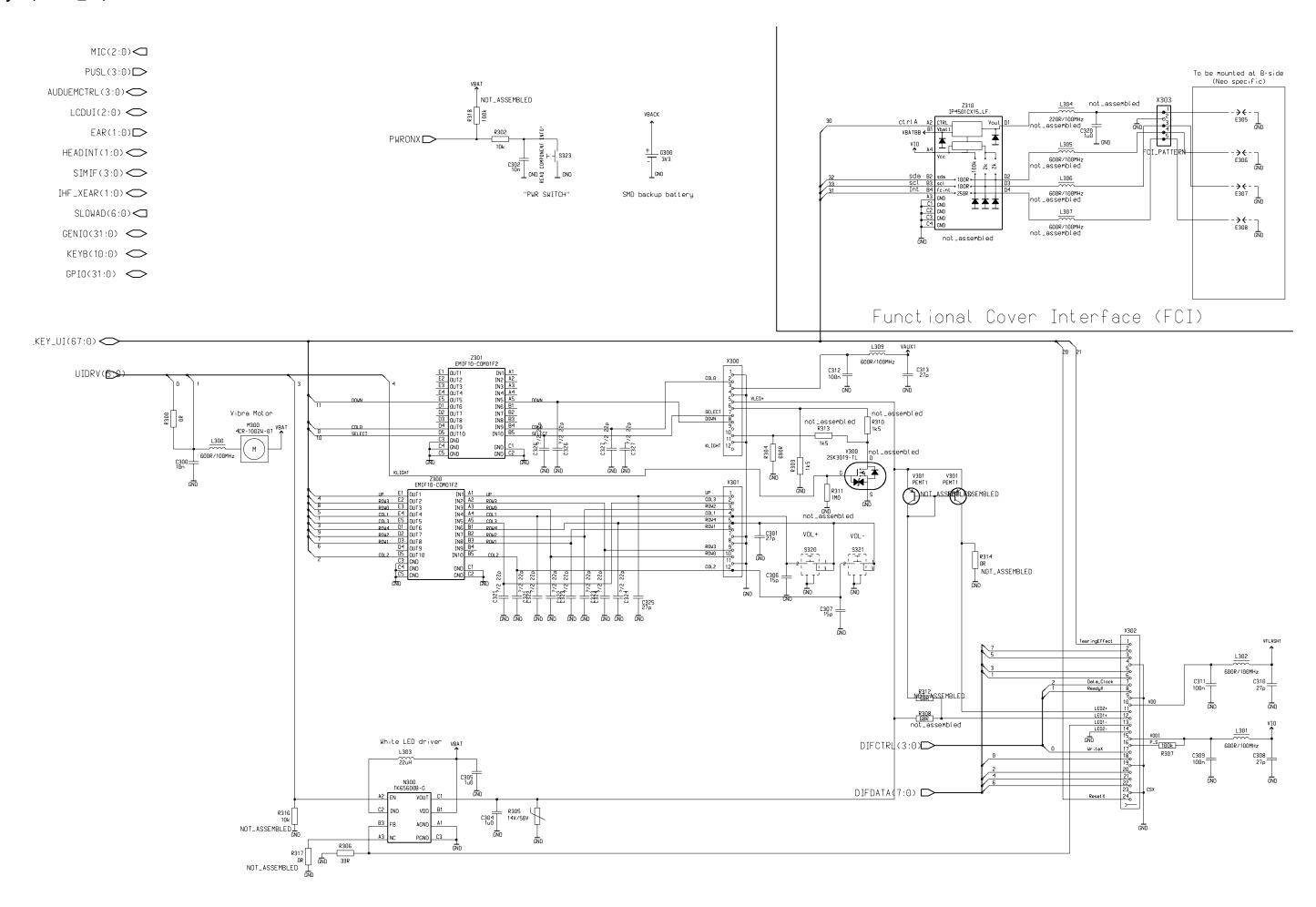
Used referenses

- C 350 353 N 350 R 350

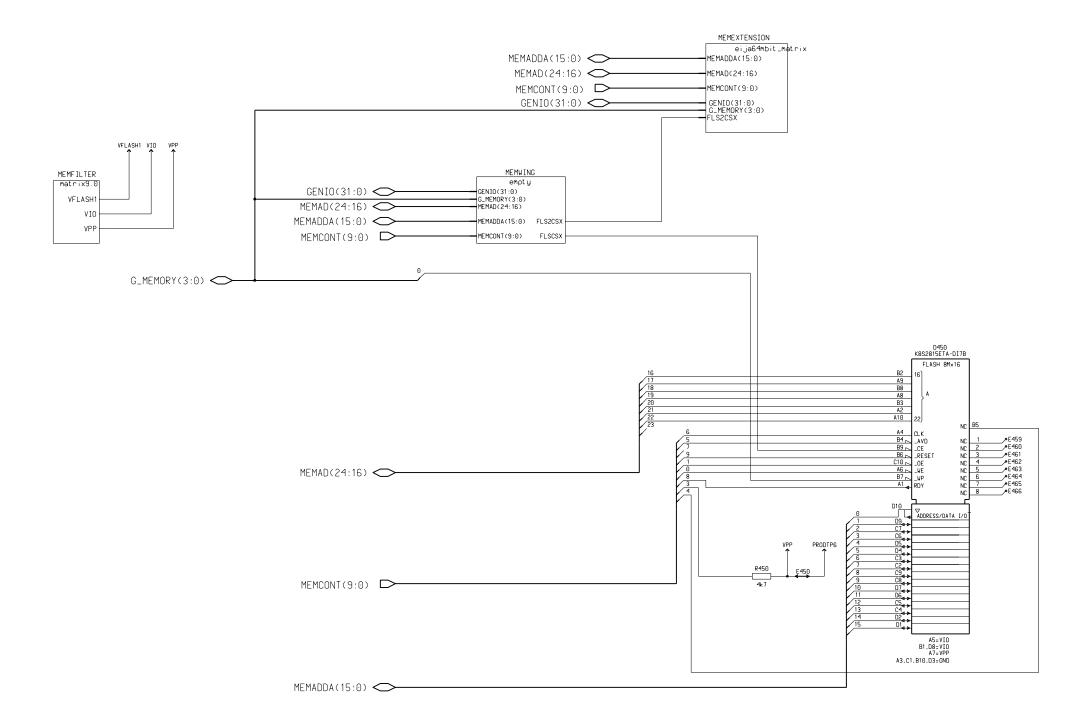
IR Resistor 1210, 1maa_02, v. 0 ed. 6



Key UI, 1maa_02, v. 1 ed. 350



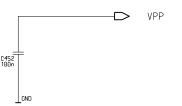
Flash Memory 128 Mbit, 1maa_02, v. 2.0 ed. 81



Discrete Capacitors for two Memories without VFlash1, 1maa_02, v. 1.3 ed. 14

Decoupling capacitors for 1st flash

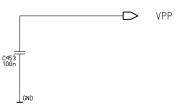


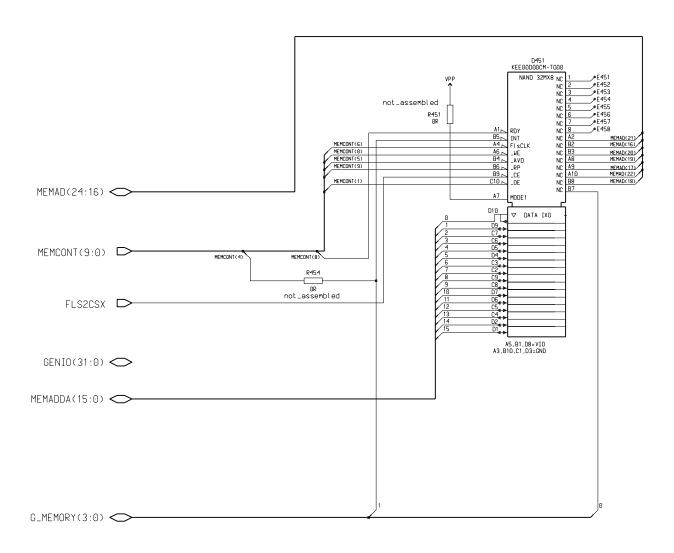


Decoupling capacitors for 2nd flash



VFLASH1

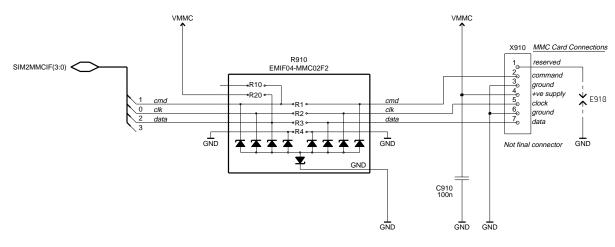




Schematics

Resistors R451 and R454 are added into schematics to make it possible to replace NAND FLASH by NOR FLASH if necessary. Later when NAND FLASH will achieve more mature state, these resistors will be removed.

In case of NAND FLASH, memory pin A7 and B7 need to be n.c. on PWB. B5 need to be connected to GENIO(13) only.

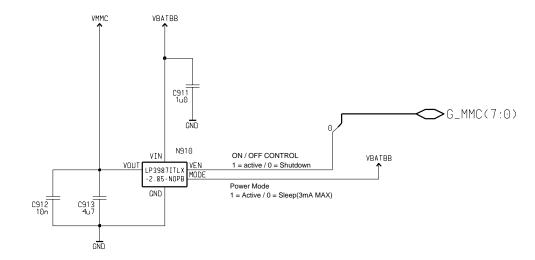


NOTE: The MMC specification imposes the following impedance limits

Command pullup resistance 4.7k to 100k Data pullup resistance 50k to 100k

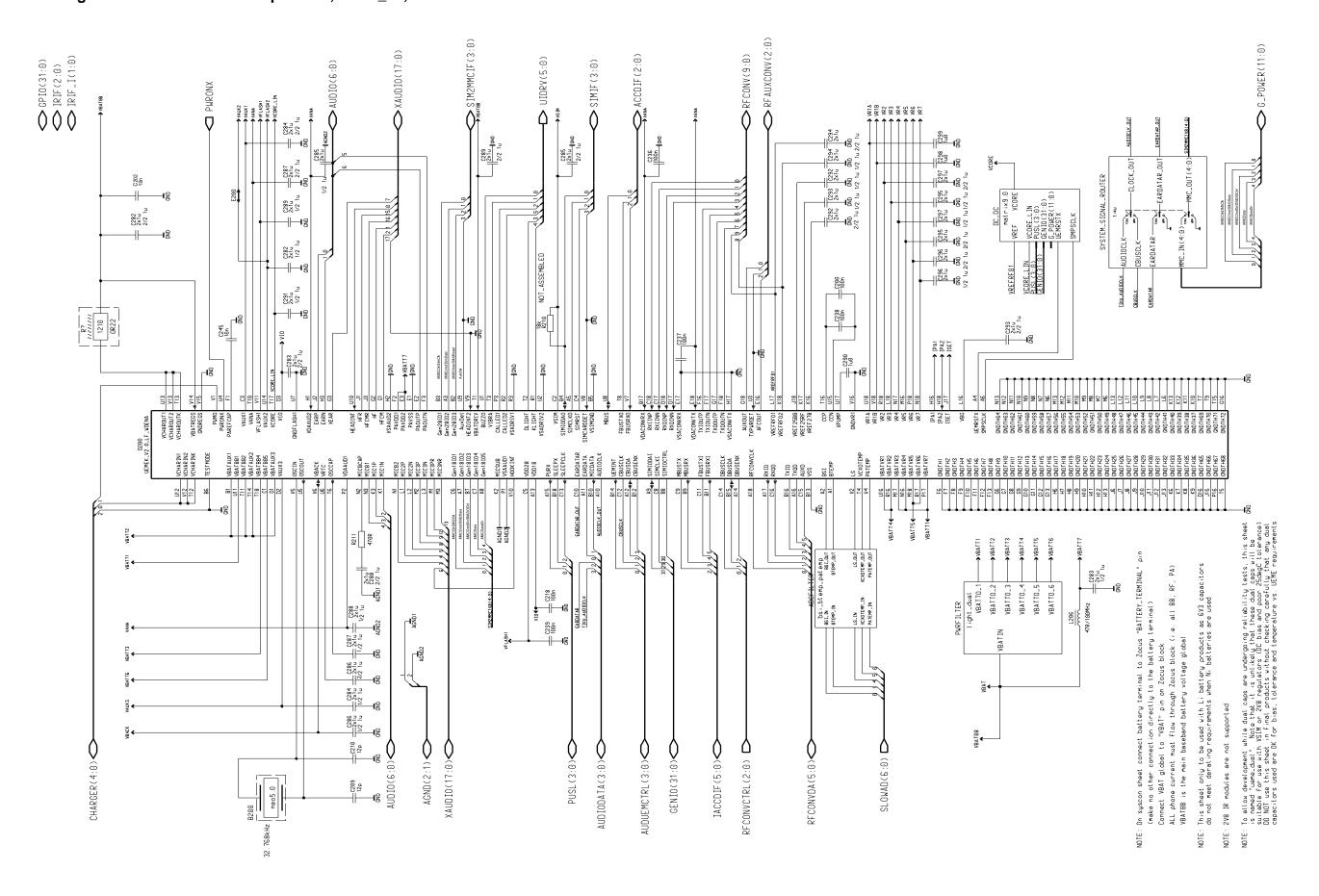
EMIF02-MMC R10=13k (therefore only suitable for command line) EMIF02-MMC R20=56k (therefore only suitable for data line) EMIF02-MMC R1/R2/R3/R4=47R

UEME includes a 13k pullup between GEN28IO2 (command) and VAUX1 so EMIF02-MMC R10 is left unconnected. UEME has no pullup on GEN28IO3 (MMC data)

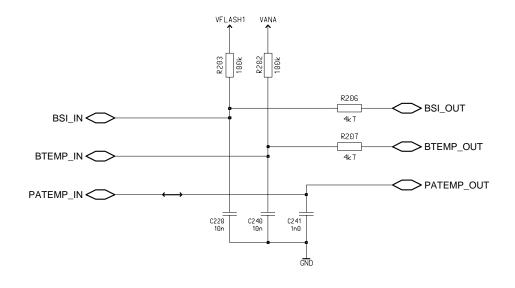


RM-72

UEME Power Management - Dual 1 uF 6V3 Capacitors, 1maa_02, v. 1.0 ed. 321



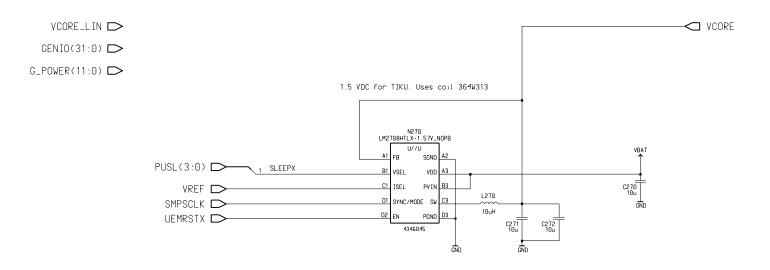
UEME ADC Filter Block - BSI, BTEMP and Active PATEMP, 1maa_02, v. 1.0



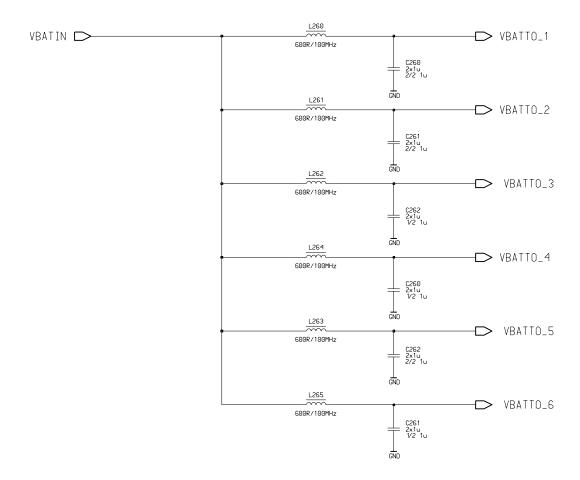


NOTE: Helga RF drives PATEMP directly so PATEMP does not need a pullup

DC_DC for TIKU and VIO, 1maa_02, v. 1.7 ed. 79

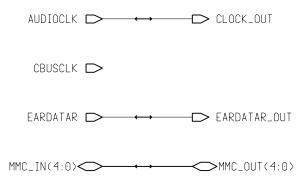


Light Filtering for Projects using 1uF Caps, 1maa_02, v. 1.0



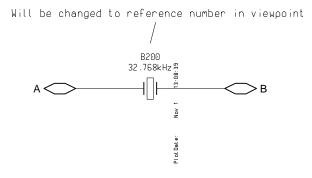
NOTE: This sheet uses dual 1uF capacitors. Check that full approval has been granted for these parts before use, or use this sheet at risk

Tiku Systems, 1maa_02, v. 1.0



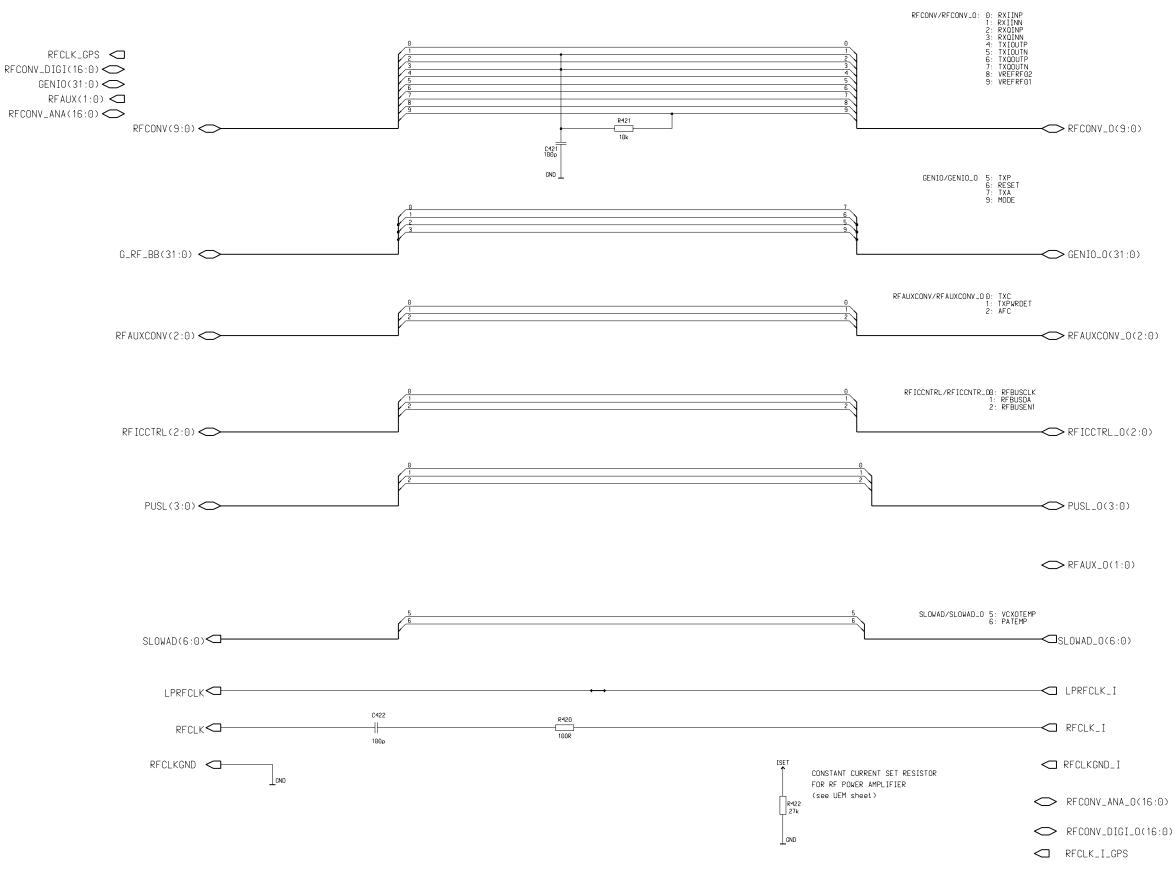
≠E916

32KHz Crystal- Micro Crystal CC4VT2, 1maa_02, v. 0 ed. 8



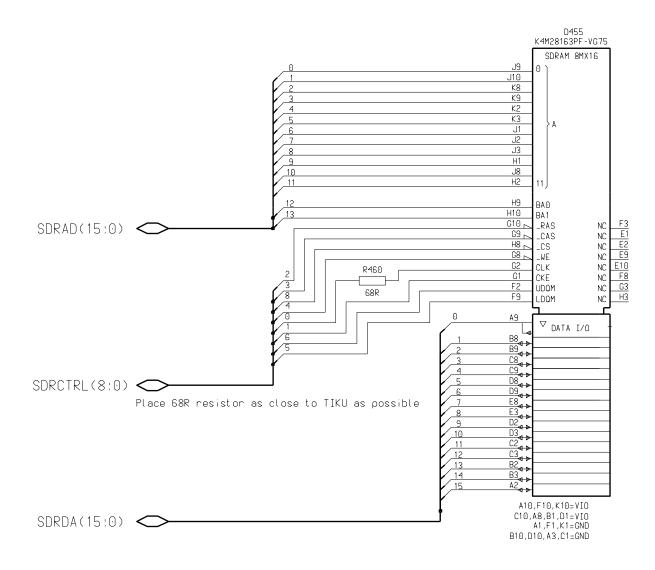
RM-72

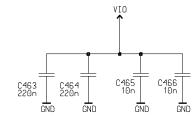
GSM RF - Baseband Interface, 1maa_02, v. 1.3 ed. 65



IPA1 AND IPA2 ARE USED IN RF, THE TOLERANCE OF R422 IS 1% (0402, 1430873)

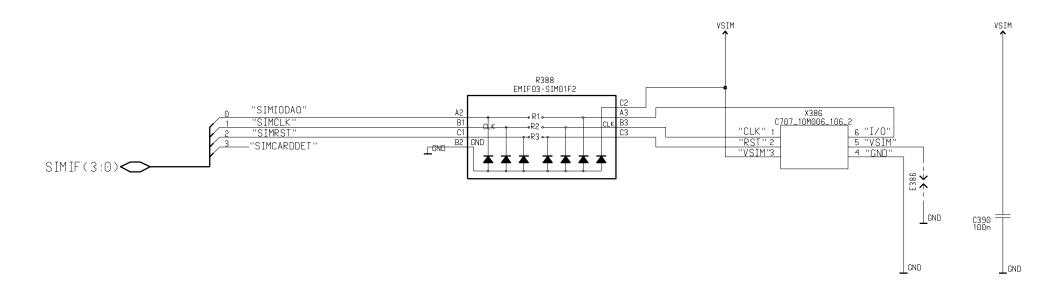
64Mbit 2V8 SDRAM Memory, 1maa_02, v. 1.0 ed. 68





PUSL(3:0)

SIM Reader, 1maa_02, v. 1.3 ed. 67

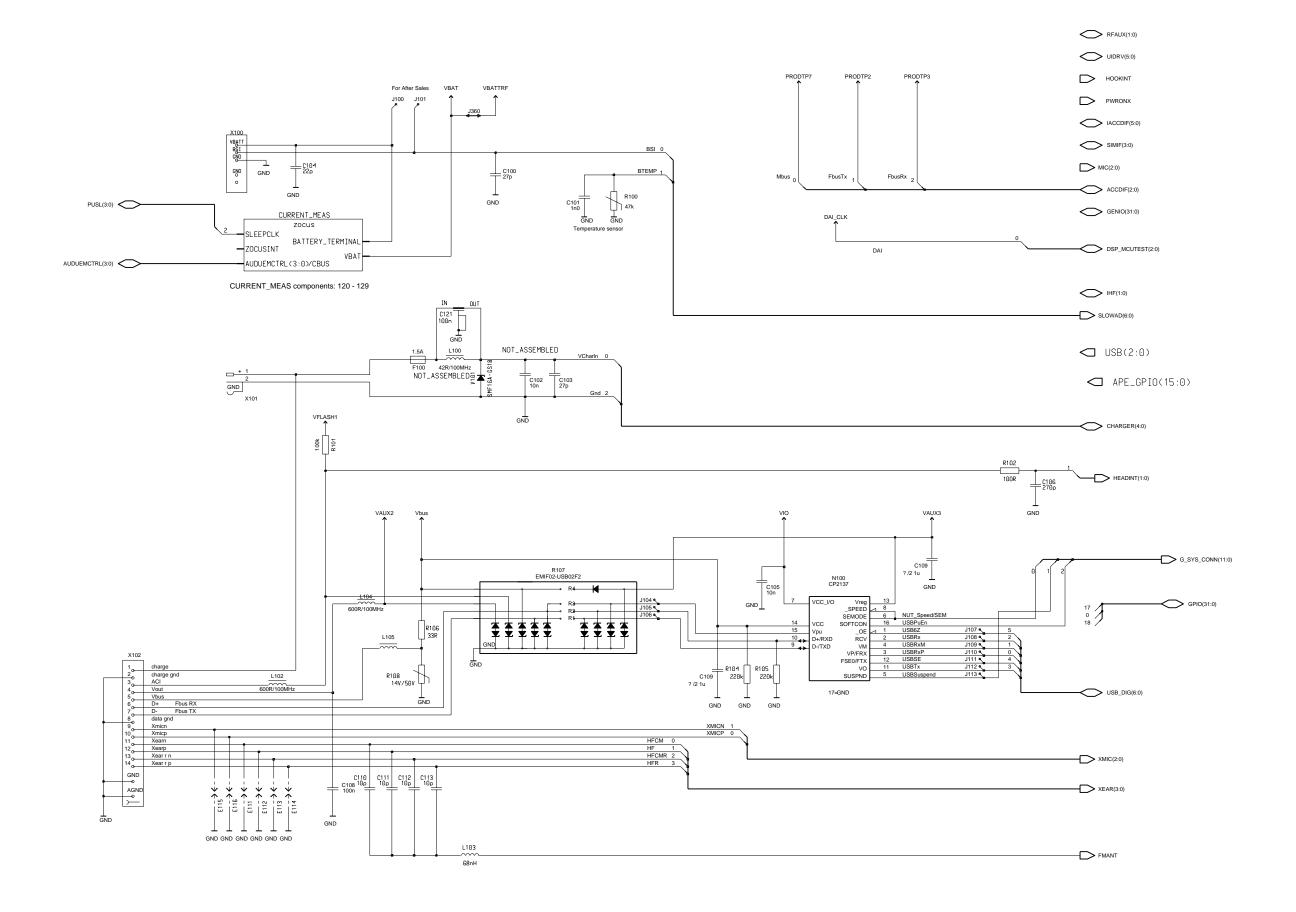


GENIO(31:0)

SIM2MMCIF(3:0)

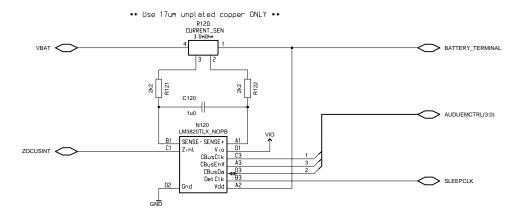
G_SIM(7:0)

System Connector, 1maa_02, v. 0.0 ed. 204

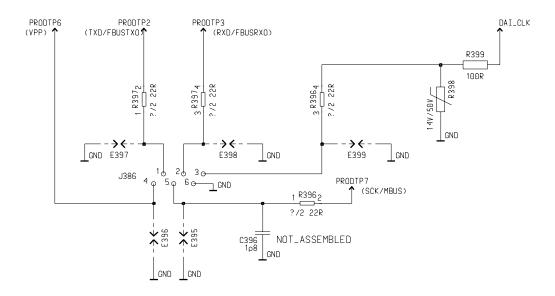


Schematics

Current Measure, 1maa_02, v. 0 ed. 19



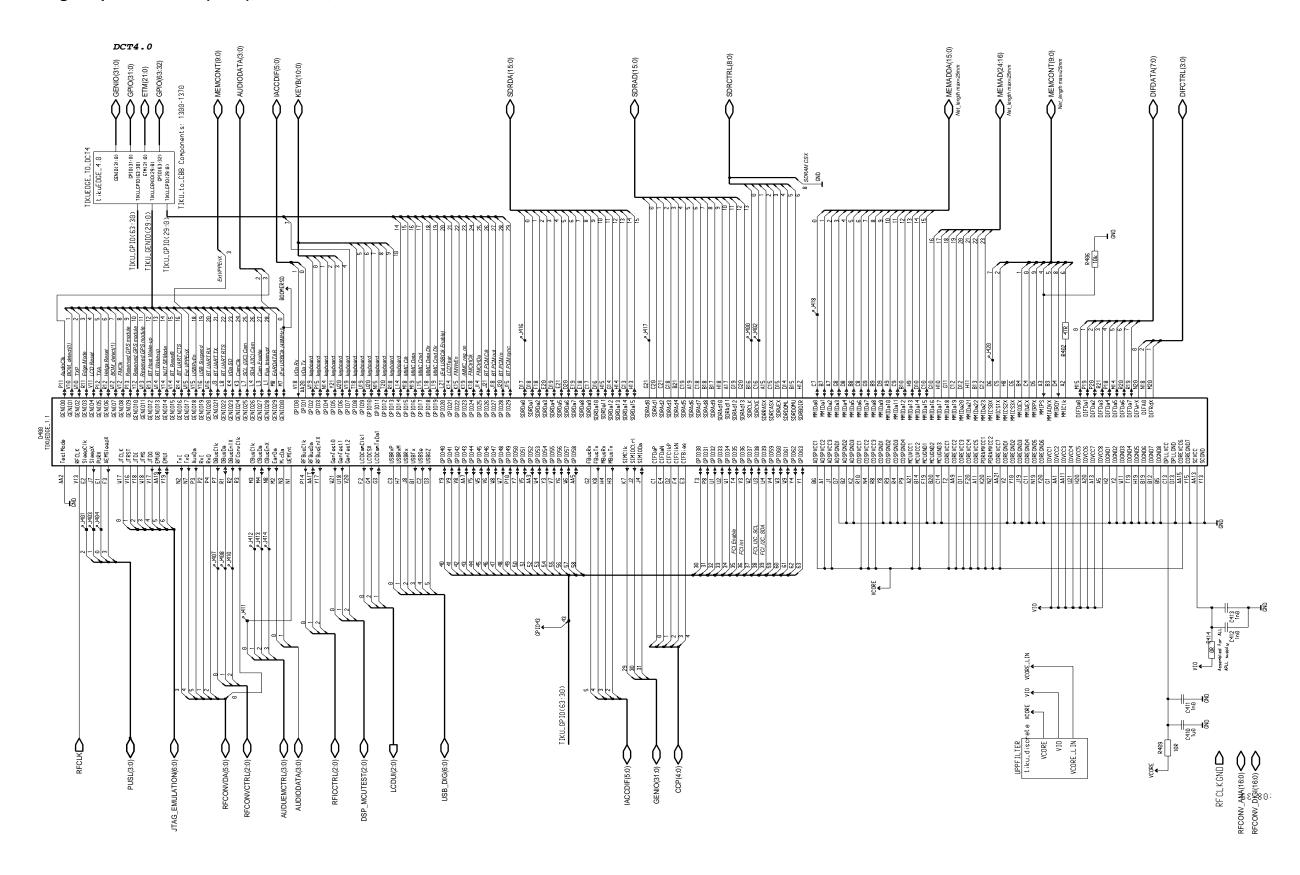
5 pin Test Pattern, 1maa_02, v. 2.0 ed. 53



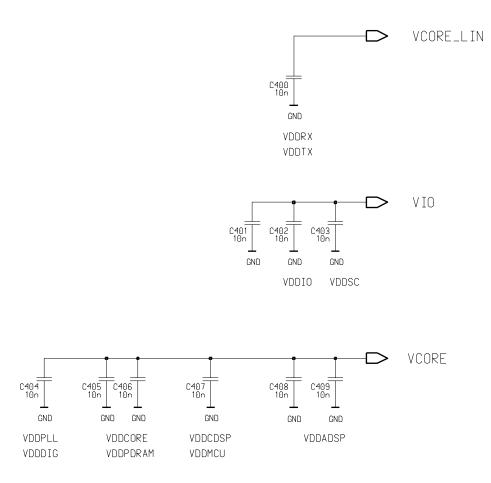
RM-72

Schematics RM-72

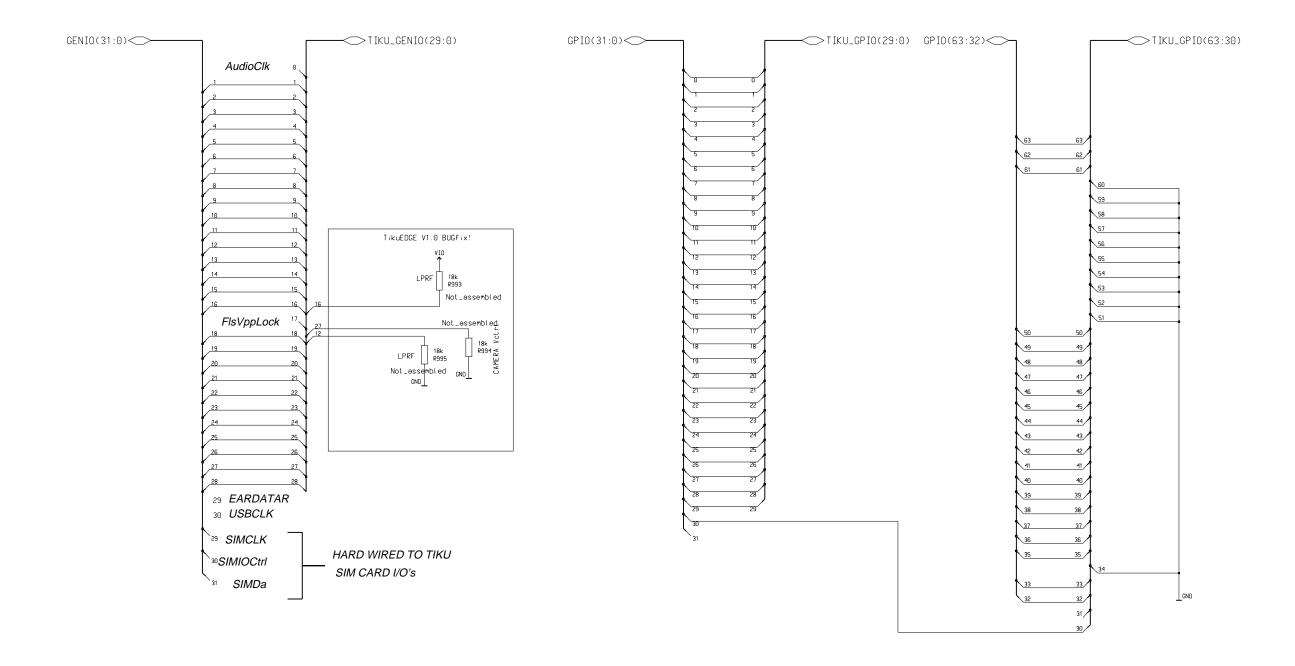
TIKUedge Implementation (GSM), 1maa_02, ed. 135



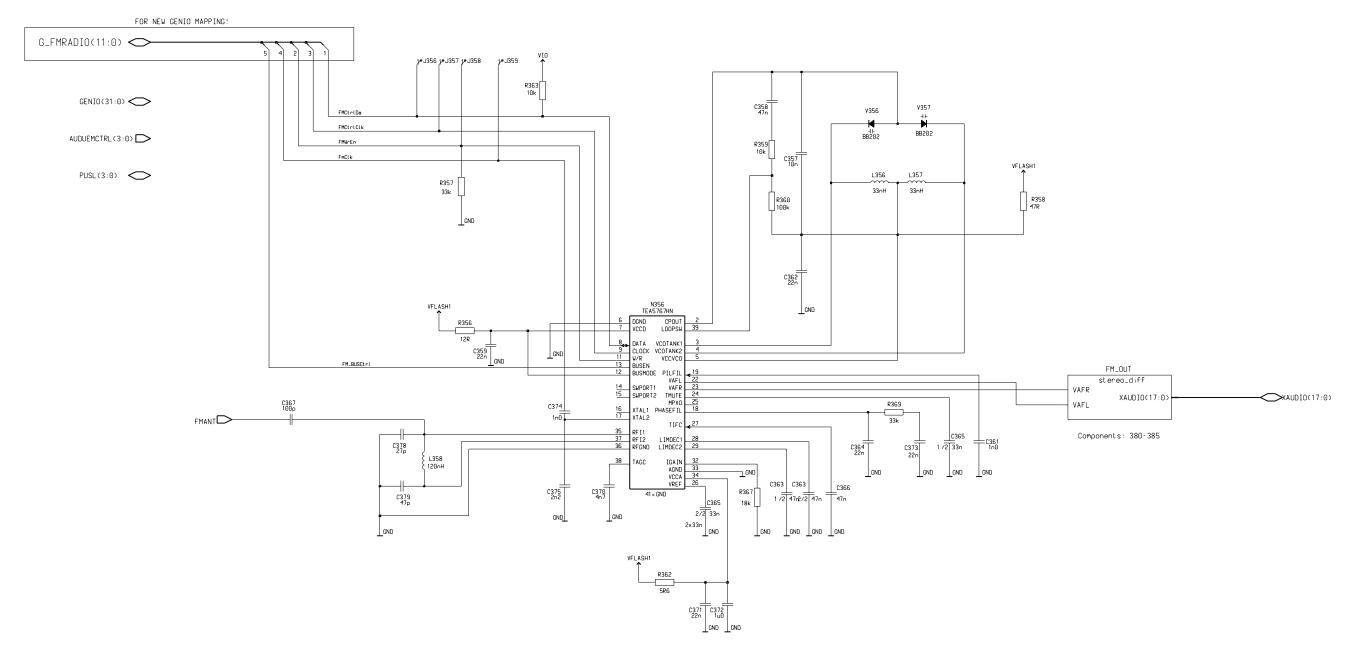
Discrete Decoupling Capacitors for Tiku, 1maa_02, v. 0 ed. 12



TikuEDGE Bus Conversion Sheet, 1maa_02, v. 1.2 ed. 104



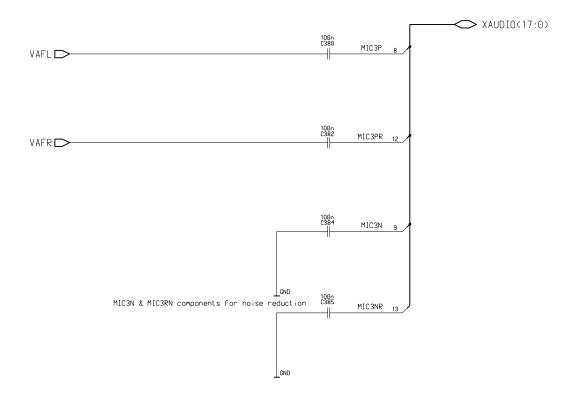
FM Radio Unit, 1maa_02, v. 1.3 ed. 199



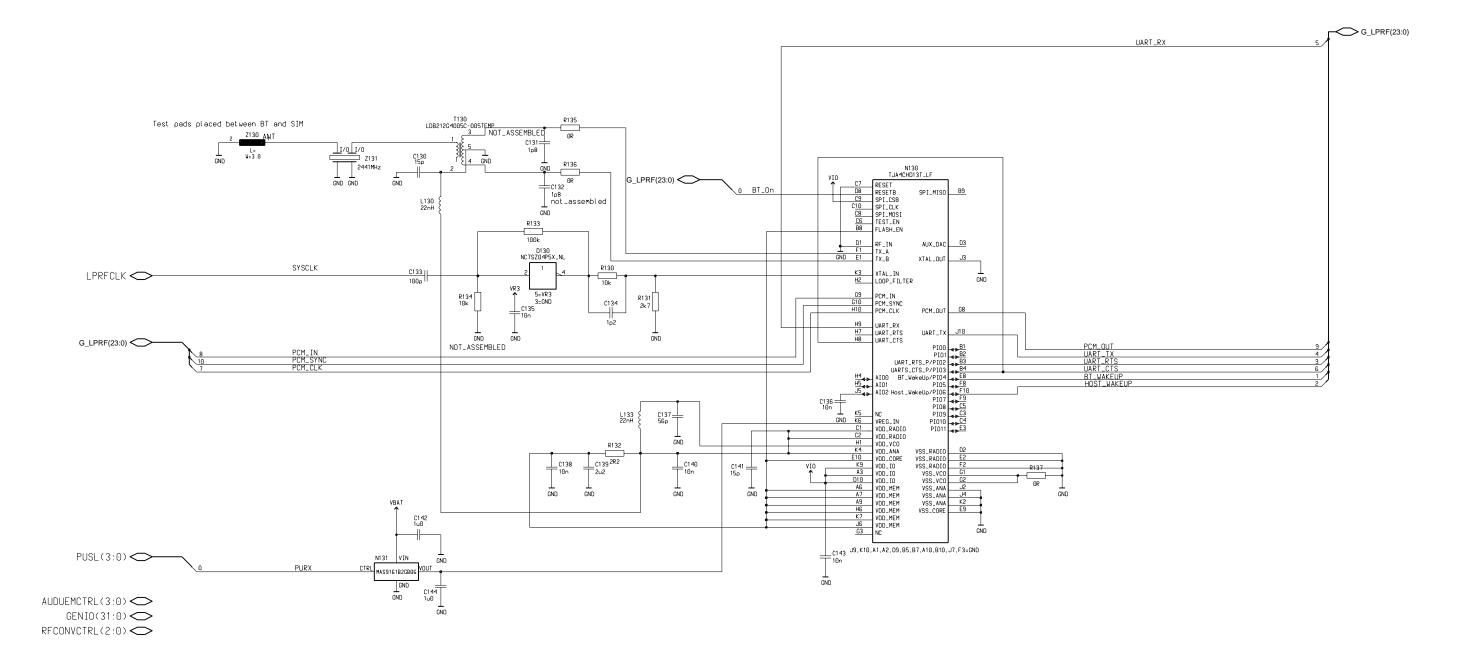
UPDATE symbol to support RDS

Notice:

C374 (1n0) and C375 (2n2) are configured for 32kHz reference clock If reference clock is 6.5MHz, use C374 (3p9) and C375 (10p)



Low Power RF Module, 1maa_02, ed. 148



RM-72

G_AUDIO(11:0)
G_APE(15:0)

 $\bigcirc G_CDMA(11:0)$ $\bigcirc G_GPS(7:0)$ $\bigcirc G_SIM(7:0)$

